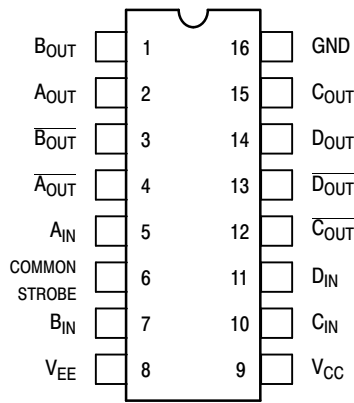
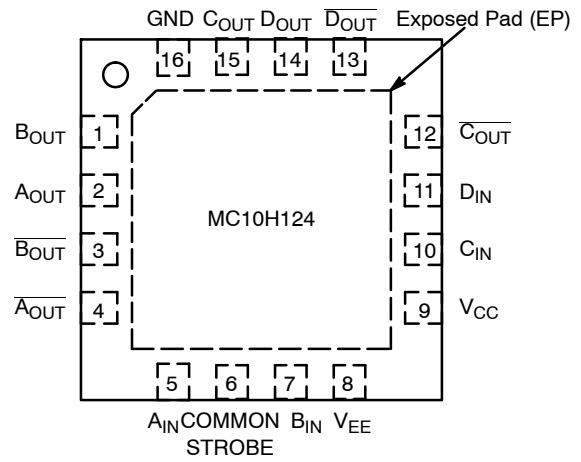


# MC10H124



Pin assignment is for Dual-in-Line Package.  
For PLCC pin assignment, see Table 1.



Pin assignment for QFN16 Package.

**Figure 2. Pin Assignment**

**Table 1. DIP CONVERSION TABLE**  
**16-Pin DIL to 20-Pin PLCC**

16 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
20 PIN PLCC	2	3	4	5	7	8	9	10	12	13	14	15	17	18	19	20

**Table 2. MAXIMUM RATINGS**

Symbol	Characteristic	Rating	Unit
$V_{EE}$	Power Supply ( $V_{CC} = 5.0$ V)	-8.0 to 0	Vdc
$V_{CC}$	Power Supply ( $V_{EE} = -5.2$ V)	0 to +7.0	Vdc
$V_I$	Input Voltage ( $V_{CC} = 5.0$ V) TTL	0 to $V_{CC}$	Vdc
$I_{out}$	Output Current – Continuous – Surge	50 100	mA
$T_A$	Operating Temperature Range	0 to +75	°C
$T_{stg}$	Storage Temperature Range – Plastic – Ceramic	-55 to +150 -55 to +165	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

# MC10H124

**Table 3. ELECTRICAL CHARACTERISTICS** ( $V_{EE} = -5.2 \text{ V} \pm 5\%$ ,  $V_{CC} = 5.0 \text{ V} \pm 5.0\%$ )

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
$I_E$	Negative Power Supply Drain Current	–	72	–	66	–	72	mA
$I_{CCH}$ $I_{CCL}$	Positive Power Supply Drain Current	–	16 25	–	16 25	–	18 25	mA
$I_R$	Reverse Current Pin 6 Pin 7	– –	200 50	– –	200 50	– –	200 50	$\mu\text{A}$
$I_F$	Forward Current Pin 6 Pin 7	– –	–12.8 –3.2	– –	–12.8 –3.2	– –	–12.8 –3.2	mA
$V_{(BR)in}$	Input Breakdown Voltage	5.5	–	5.5	–	5.5	–	Vdc
$V_I$	Input Clamp Voltage	–	–1.5	–	–1.5	–	–1.5	Vdc
$V_{OH}$	High Output Voltage	–1.02	–0.84	–0.98	–0.81	–0.92	–0.735	Vdc
$V_{OL}$	Low Output Voltage	–1.95	–1.63	–1.95	–1.63	–1.95	–1.60	Vdc
$V_{IH}$	High Input Voltage	2.0	–	2.0	–	2.0	–	Vdc
$V_{IL}$	Low Input Voltage	–	0.8	–	0.8	–	0.8	Vdc

1. Each MECL 10H™ series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfm is maintained. Outputs are terminated through a 50  $\Omega$  resistor to –2.0 V.

**Table 4. AC CHARACTERISTICS**

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
$t_{pd}$	Propagation Delay	0.55	2.5	0.55	2.65	0.85	3.1	ns
$t_r$	Rise Time	0.5	1.5	0.5	1.6	0.5	1.7	ns
$t_f$	Fall Time	0.5	1.5	0.5	1.6	0.5	1.7	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

# MC10H124

## APPLICATIONS INFORMATION

The MC10H124 has TTL-compatible inputs and MECL complementary open-emitter outputs that allow use as an inverting/non-inverting translator or as a differential line driver. When the common strobe input is at the low-logic level, it forces all true outputs to a MECL low-logic state and all inverting outputs to a MECL high-logic state.

An advantage of this device is that TTL-level information can be transmitted differentially, via balanced twisted pair lines, to MECL equipment, where the signal can be received by the MC10H115 or MC10H116 differential line receivers. The power supply requirements are ground, +5.0 V, and -5.2 V.

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC10H124FN	PLCC-20	46 Units / Rail
MC10H124FNG	PLCC-20 (Pb-Free)	46 Units / Rail
MC10H124FNR2	PLCC-20	500 / Tape & Reel
MC10H124FNR2G	PLCC-20 (Pb-Free)	500 / Tape & Reel
MC10H124L	CDIP-16	25 Units / Rail
MC10H124M	SOEIAJ-16	50 Units / Rail
MC10H124MG	SOEIAJ-16 (Pb-Free)	50 Units / Rail
MC10H124MEL	SOEIAJ-16	2000 / Tape & Reel
MC10H124MELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel
MC10H124P	PDIP-16	25 Units / Rail
MC10H124PG	PDIP-16 (Pb-Free)	25 Units / Rail
MC10H125MNG	QFN-16, 3 x 3 mm (Pb-Free)	123 Units / Rail
MC10H124MNTXG	QFN-16, 3 x 3 mm (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

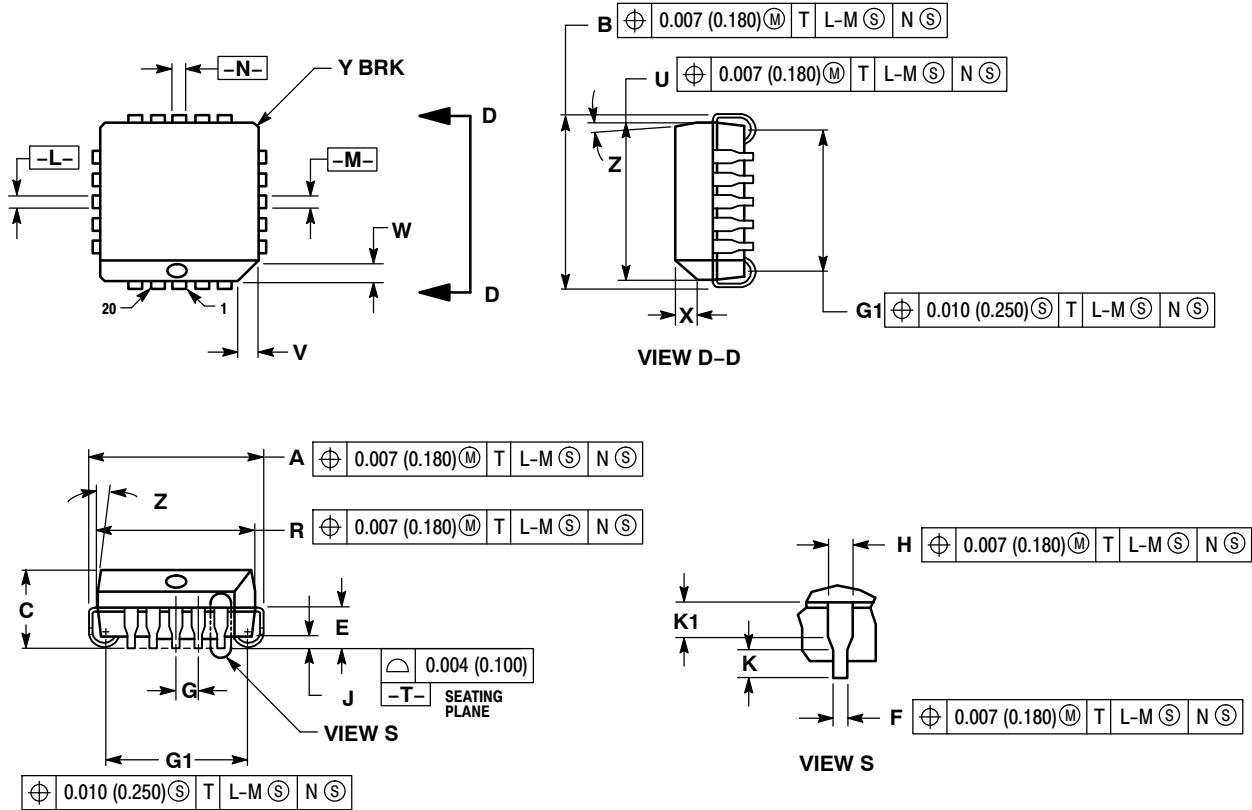
## Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

# MC10H124

## PACKAGE DIMENSIONS

20 LEAD PLLC  
CASE 775-02  
ISSUE F



### NOTES:

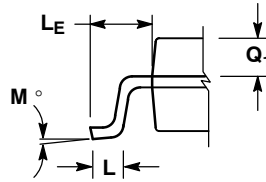
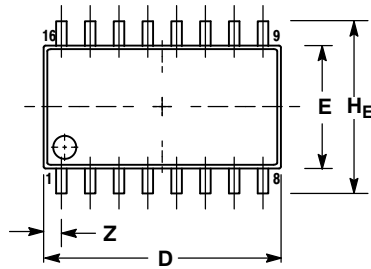
1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
2. DIMENSIONS IN INCHES.
3. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

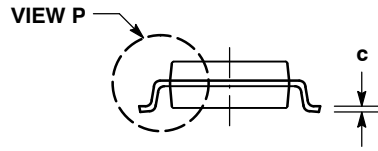
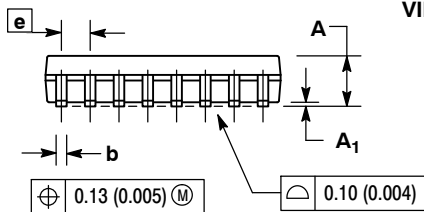
# MC10H124

## PACKAGE DIMENSIONS

### SOEIAJ-16 CASE 966-01 ISSUE A



DETAIL P

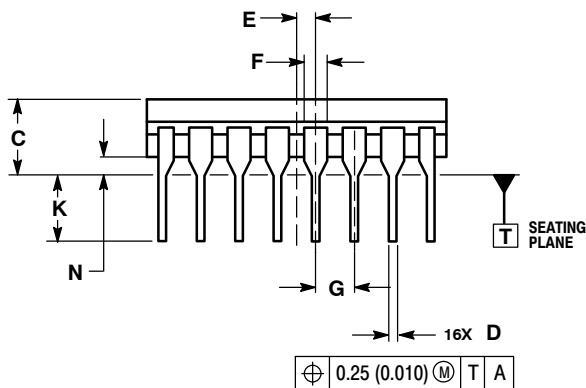
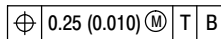
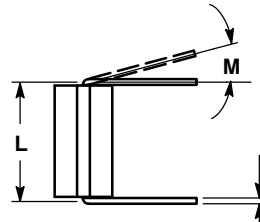
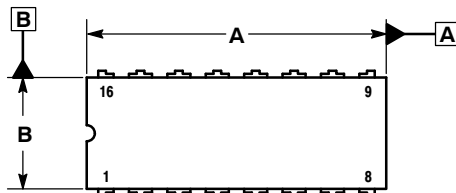


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H <sub>E</sub>	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L <sub>E</sub>	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

### CDIP-16 L SUFFIX CERAMIC DIP PACKAGE CASE 620A-01 ISSUE O



#### NOTES:

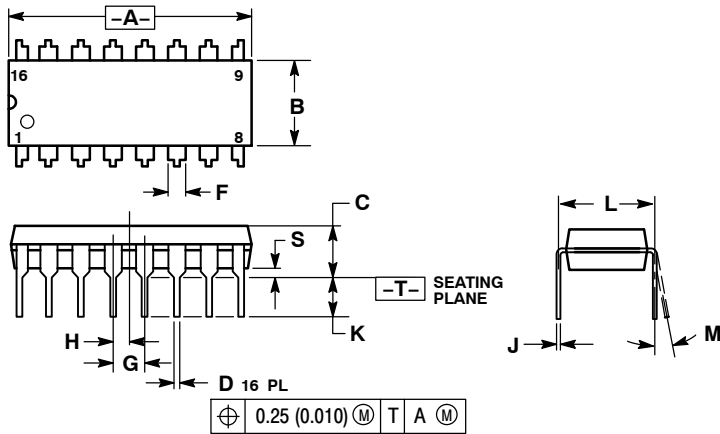
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.
5. THIS DRAWING REPLACES OBSOLETE CASE OUTLINE 620-10.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	---	0.200	---	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

# MC10H124

## PACKAGE DIMENSIONS

PDIP-16  
CASE 648-08  
ISSUE T



### NOTES:

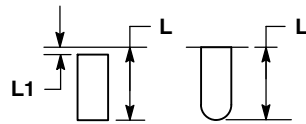
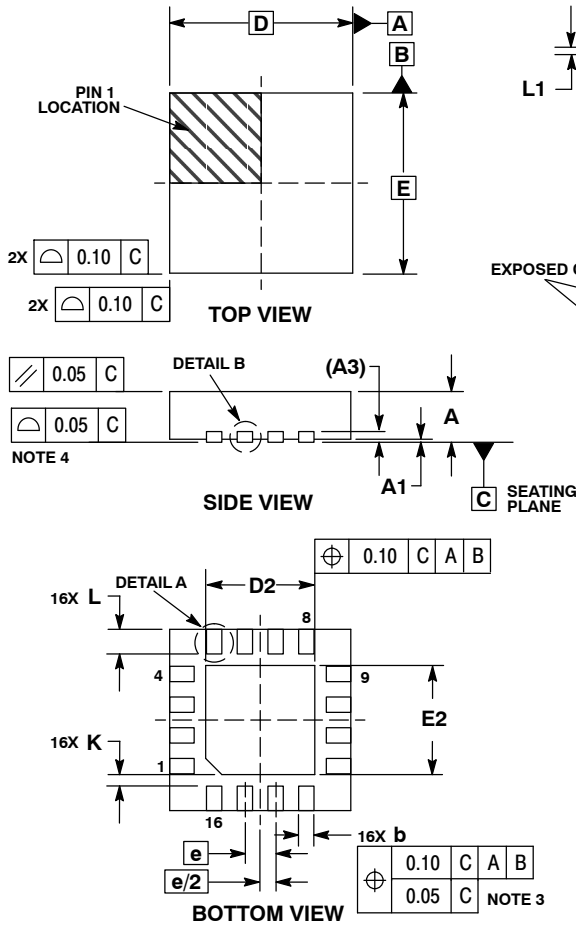
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

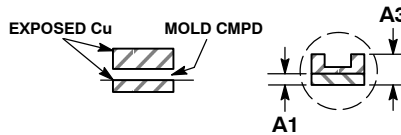
# MC10H124

## PACKAGE DIMENSIONS

QFN16 3x3, 0.5P  
CASE 485G-01  
ISSUE E



**DETAIL A**  
ALTERNATE TERMINAL CONSTRUCTIONS

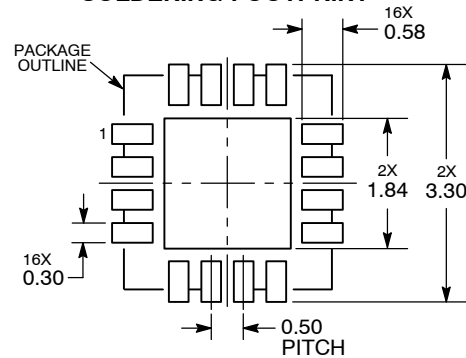


**DETAIL B**  
ALTERNATE CONSTRUCTIONS

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
  4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.18	0.30
D	3.00	BSC
D2	1.65	1.85
E	3.00	BSC
E2	1.65	1.85
e	0.50	BSC
K	0.18	TYP
L	0.30	0.50
L1	0.00	0.15


### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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